L Number	Hits	Search T xt	DB	Tim stamp
	3367	(wiring near layer) near10 lectrode n ar10	USPAT;	2004/01/07
		(connect or connecting or connected or	US-PGPUB;	12:21
		connection or bump)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	867	(wiring near layer) near10 electrode near10	USPAT;	2004/01/07
		(connect or connecting or connected or	US-PGPUB;	12:21
		connection or bump) near10 (insulation or	EPO; JPO;	
		insulating or dielectric)	DERWENT;	
			IBM_TDB	
-	137	((wiring near layer) near10 electrode near10	USPAT;	2004/01/07
	i e	(connect or connecting or connected or	US-PGPUB;	12:22
		connection or bump) near10 (insulation or	EPO; JPO;	
		insulating or dielectric)).clm.	DERWENT;	
			IBM_TDB	
	16	((wiring near layer) near10 electrode near10	USPAT;	2004/01/07
		(connect or connecting or connected or	US-PGPUB;	12:25
		connection or bump) near10 (insulation or	EPO; JPO;	
		insulating or dielectric)).clm. and	DERWENT;	
		solder.clm.	IBM_TDB	
	137	((wiring near layer) near10 electrode near10	USPAT;	2004/01/07
		(connect or connecting or connected or	US-PGPUB;	12:25
		connection or bump) near10 (insulation or	EPO; JPO;	
		insulating or dielectric)).clm.	DERWENT;	
			IBM_TDB	
•	63	((wiring near layer) near5 electrode near5	USPAT;	2004/01/07
		(connect or connecting or connected or	US-PGPUB;	12:26
		connection or bump) near5 (insulation or	EPO; JPO;	
		insulating or dielectric)).clm.	DERWENT;	
			IBM_TDB	
•	63	(electrode near5 (wiring near layer) near5	USPAT;	2004/01/07
		(connect or connecting or connected or	US-PGPUB;	12:26
		connection or bump) near5 (insulation or	EPO; JPO;	
		insulating or dielectric)).clm.	DERWENT;	
		,	IBM_TDB	
	1	(electrode near5 (wiring nea layer) near5	USPAT;	2004/01/07
		(connect or connecting or connected or	US-PGPUB;	12:27
		connection or bump) near5 (connection	EPO; JPO;	
		near member)).clm.	DERWENT;	
		<i>"</i>	IBM_TDB	
_	4	(electrode near5 (wiring near layer) near5	USPAT;	2004/01/07
		(connect or connecting or connected or	US-PGPUB;	12:27
		connection or bump) near5 (connection	EPO; JPO;	
		near (member or structure))).clm.	DERWENT;	
		· · · · · · · · · · · · · · · · · · ·	IBM_TDB	
_	313	(electr de near5 (wiring near layer) near5	USPAT;	2004/01/07
		(c nnect r connecting or connected or	US-PGPUB;	12:27
		conn cti n r bump)).clm.	EPO; JPO;	- -
			DERWENT;	
İ			IBM_TDB	.~_

-	47	(electrode near5 (wiring near layer) near5	USPAT;	2004/01/07
		(conn ct or connecting or connect d or	US-PGPUB;	12:28
		conn cti n r bump)).clm. and (electrode	EPO; JPO;	
		near5 (wiring near layer) near5 (connect or	DERWENT;	
		connecting or connected or connection or	IBM_TDB	
		bump)).ab.	.55	
-	3	(electrode near5 (wiring near layer) near5	USPAT;	2004/01/07
		(connect or connecting or connected or	US-PGPUB;	12:29
		connection or bump)).clm. and (electrode	EPO; JPO;	
		near5 (wiring near layer) near5 (connect or	DERWENT;	
		connecting or connected or connection or	IBM_TDB	
		bump)).ab. and solder.clm.		
_	3	(electrode near5 (wiring near layer) near5	USPAT;	2004/01/07
	,	(connect or connecting or connected or	US-PGPUB;	12:29
		connection or bump)).clm. and solder.clm.	EPO; JPO;	
		and bump.clm.	DERWENT;	
			IBM_TDB	
-	20	(electrode near5 (wiring near layer) near5	USPAT;	2004/01/07
		(connect or connecting or connected or	US-PGPUB;	12:30
•		connection or bump)).clm. and solder.clm.	EPO; JPO;	
	*		DERWENT;	
		x	IBM_TDB	
-	49	(electrode near5 (wiring near layer) near5	USPAT;	2004/01/07
		(connect or connecting or connected or	US-PGPUB;	12:31
		connection or bump)).clm. and solder and	EPO; JPO;	
		bump and (au or gold)	DERWENT;	
•		-	IBM_TDB	
-	48	(electrode near5 (wiring near layer) near5	USPAT;	2004/01/07
	-	(connect or connecting or connected or	US-PGPUB;	12:31
		connection or bump)).clm. and solder and	EPO; JPO;	
		bump and (au or gold) and (insulation or	DERWENT;	
8		insulating or dielectric)	IBM_TDB	
•	29	((electrode near5 (wiring near layer) near5	USPAT;	2004/01/07
		(connect or connecting or connected or	US-PGPUB;	12:32
		connection or bump)) same (insulating or	EPO; JPO;	
		insulation or dielectric)).clm. and solder	DERWENT;	
		and bump and (au or gold) and (insulation or	IBM_TDB	
		insulating or dielectric)		
-	28	((electrode near5 (wiring near layer) near5	USPAT;	2004/01/07
		(connect or connecting or connected or	US-PGPUB;	12:32
		connection or bump)) same (insulating or	EPO; JPO;	
		insulation or dielectric)).clm. and solder	DERWENT;	
		and bump and (au or gold) and (insulation or	IBM_TDB	
		insulating or dielectric) and (laminate or		
		laminated or laminating or lamination or		
		plate r plating or plated)		

		(/ 1	LICDAT	2004/04/07
-	14	((electrode near5 (wiring near lay r) near5	USPAT; US-PGPUB;	2004/01/07 12:39
		(connect r connecting or connected r	·	12:39
		connection or bump)) sam (insulating r	EPO; JPO;	
		insulation or dielectric)).clm. and solder	DERWENT;	
		and bump and (au or gold) and (insulation or	IBM_TDB	
		insulating or dielectric) and (laminate or		
		laminated or laminating or lamination or		
		plate or plating or plated) and ((au or gold)		ie.
		near5 bump)		0004/04/07
-	3	((electrode near5 (wiring near layer) near5	USPAT;	2004/01/07
		(connect or connecting or connected or	US-PGPUB;	12:40
		connection or bump)) same (insulating or	EPO; JPO;	
		insulation or dielectric)).clm. and	DERWENT;	
		solder.clm. and bump and (au or gold) and	IBM_TDB	
		(insulation or insulating or dielectric) and		
		(laminate or laminated or laminating or		
		lamination or plate or plating or plated) and		
		((au or gold) near5 bump)		0004/04/07
-	6	((electrode near5 (wiring near layer) near5	USPAT;	2004/01/07
		(connect or connecting or connected or	US-PGPUB;	12:41
		connection or bump))).clm. and solder.clm.	EPO; JPO;	
		and bump and (au or gold) and (insulation or	DERWENT;	
		insulating or dielectric) and (laminate or	IBM_TDB	
		laminated or laminating or lamination or		
		plate or plating or plated) and ((au or gold)		
	_	near5 bump)		0004/04/08
-	3	((electrode near5 (wiring near layer) near5	USPAT;	2004/01/07
*		(connect or connecting or connected or	US-PGPUB;	12:41
		connection or bump))).clm. and solder.clm.	EPO; JPO;	
		and bump.clm. and (insulation or insulating	DERWENT;	
		or dielectric) and (laminate or laminated or	IBM_TDB	
		laminating or lamination or plate or plating		
		or plated)	LICRAT	2004/01/07
-	3	((electrode near5 (wiring near layer) near5	USPAT; US-PGPUB;	
		(connect or connecting or connected or	•	12:41
		connection or bump))).clm. and solder.clm.	EPO; JPO;	
		and bump.clm. and (insulation or insulating	DERWENT;	
	30	or dielectric).clm. ((electrode near5 (wiring near layer) near5	IBM_TDB USPAT;	2004/01/07
-	20	((electrode nears (wiring near layer) nears (connect or connecting or connected or	US-PGPUB;	12:43
		connection or bump))).clm. and solder.clm.	EPO; JPO;	12.75
		and (insulation or insulating or	DERWENT;	
		dielectric).clm.	IBM TDB	
	99	((electrode near5 (wiring) near5 (connect or	USPAT;	2004/01/07
	77	connecting or connected or connection or	US-PGPUB;	12:43
1		bump))).clm. and solder.clm. and (insulation	EPO; JPO;	12.70
		or insulating or dielectric).clm.	DERWENT;	
	a.	or mediating of diesectric).Clill.	IBM_TDB	
	49	((lectrode near5 (wiring) near5 (c nn ct r	USPAT;	2004/01/07
_	43	c nnecting or connected or c nnection or	US-PGPUB;	12:43
		bump))).clm. and s lder.clm. and (insulati n	EPO; JPO;	12.75
		or insulating r dielectric).clm. and	DERWENT;	
		bump.clm.	IBM_TDB	
L		wampiolini	10111_100	

_	7	((lectrode near5 (wiring) n ar5 (connect or	USPAT;	2004/01/07
		conn cting or connected or connection or	US-PGPUB;	12:43
		bump))).clm. and s Ider.clm. and (insulation	EPO; JPO;	
		or insulating or dielectric).clm. and	DERWENT;	
		bump.clm. and (wire near10 (plate or	IBM_TDB	
		plating or plated or laminate or laminated	_	
		or laminating or lamination))		
_	23	((electrode near5 (wiring) near5 (connect or	USPAT;	2004/01/07
		connecting or connected or connection or	US-PGPUB;	12:44
		bump))).clm. and solder.clm. and (insulation	EPO; JPO;	
		or insulating or dielectric).clm. and	DERWENT;	
		bump.clm. and (wiring near10 (plate or	IBM_TDB	
		plating or plated or laminate or laminated	_	
		or laminating or lamination))		
_	17	((electrode near5 (wiring) near5 (connect or	USPAT:	2004/01/07
ē		connecting or connected or connection or	US-PGPUB;	12:44
	٠	bump))).clm. and solder.clm. and (insulation	EPO; JPO;	
		or insulating or dielectric).clm. and	DERWENT;	:
		bump.clm. and (wiring near10 (plate or	IBM_TDB	
		plating or plated or laminate or laminated		
		or laminating or lamination)).clm.		
_	1 1	((electrode near5 (wiring) near5 (connect or	USPAT;	2004/01/07
	-	connecting or connected or connection or	US-PGPUB;	12:44
		bump))).clm. and solder.clm. and (insulation	EPO; JPO;	
		or insulating or dielectric).clm. and	DERWENT;	
		bump.clm. and (wiring near10 (plate or	IBM_TDB	•
		plating or plated or laminate or laminated		
		or laminating or lamination)).clm. and		
		(bump near5 (au or gold)).clm.		
_	4	((electrode near5 (wiring) near5 (connect or	USPAT;	2004/01/07
		connecting or connected or connection or	US-PGPUB;	12:45
		bump))).clm. and solder.clm. and (insulation	EPO; JPO;	12.10
		or insulating or dielectric).clm. and	DERWENT;	*
		bump.clm. and (wiring near10 (plate or	IBM_TDB	
		plating or plated or laminate or laminated		
		or laminating or lamination)).clm. and		
		(bump near5 (au or gold))		
_	9	((electrode near5 (wiring) near5 (connect or	USPAT:	2004/01/07
		connecting or connected or connection or	US-PGPUB;	12:46
		bump))).clm. and solder.clm. and (insulation	EPO; JPO;	12.10
		or insulating or dielectric).clm. and	DERWENT;	
		bump.clm. and (wiring near10 (plate or	IBM TDB	
		plating or plated or laminate or laminated	10111_100	
		or laminating or lamination)).clm. and		
,		electrode.ab.		
	ì	((electrode.ab. ((electr de near5 (wiring) near5 (c nnect r	USPAT;	2004/01/07
_	<u>ρ</u>	Horora ac near Aming) hear to infect t	,,	
-	8	c nnecting reconnect dione nnection r	US-PGPIIR.	12:46
-	8	c nnecting r connect d or c nnecti n r	US-PGPUB; EPO: JPO:	12:46
•	8	bump))).clm. and s lder.clm. and (insulati n	EPO; JPO;	12:46
-	8	bump))).clm. and s lder.clm. and (insulati n or insulating or diel ctric).clm. and	EPO; JPO; DERWENT;	12:46
•	8	bump))).clm. and s lder.clm. and (insulati n or insulating or diel ctric).clm. and bump.clm. and (wiring near10 (plate or	EPO; JPO;	12:46
•	8	bump))).clm. and s lder.clm. and (insulati n or insulating or diel ctric).clm. and	EPO; JPO; DERWENT;	12:46